

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

03.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: Pinlamination

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	214		2
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3
		70	L2	
C-STD-FR4-ML-0.203mm-070+070-TG150-H...	50203119	203		4
		70	L3	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	214		5
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		7
		70	L4	
C-STD-FR4-ML-0.203mm-070+070-TG150-H...	50203119	203		8
		70	L5	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	214		9
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		10
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		11
		70	L6	
C-STD-FR4-ML-0.203mm-070+070-TG150-H...	50203119	203		12
		70	L7	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	214		13
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		14
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	15

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1921 µm

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